



Product Change Notification

CN-202407002F

**Issue date:** 08 Jul 2024  
**Effective date:** 20 Oct 2024

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Introduction of Cu-wire for ESD protection devices in SOT23 (Part 1)

Change Category

<input checked="" type="checkbox"/> Wafer	<input checked="" type="checkbox"/> Assembly			
<input type="checkbox"/> Process	<input type="checkbox"/> Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer	<input checked="" type="checkbox"/> Assembly	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Materials	<input type="checkbox"/> Materials	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Wafer	<input type="checkbox"/> Assembly			
<input type="checkbox"/> Location	<input type="checkbox"/> Location			

Details of this change

Scheduled changes affect ESD protection devices in SOT23. These include:

- Bond wire material will be changed from gold (Au) to copper (Cu).
- 200mm wafers will be introduced as replacement for the currently

released 150mm wafers. Additionally a new die design and improved back side metallization will be implemented.

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CN-202407002F\_PCN-FORM-Rev\_5\_0\_2.xlsm:  
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### **Why do we implement this change?**

Nexperia continues to introduce copper bonding wire for plastic SMD packages to enhance mechanical properties and maintain latest wire bonding technology.  
Release of 200mm wafer diameter material will help to safeguard supply chain.

### **Identification of affected products**

Changed products can be identified by date code after implementation.

## **Management summary**

Introduction of Cu wire and supply extension by release of 200mm wafer diameter to ESD protection devices in SOT23. The products receive new die design and change of wafer backside metallization.

## **Product availability**

### **Production**

Planned first shipment: 21 Oct 2024

Existing inventory will be shipped until depleted

### **Sample information**

Samples are available upon request

## Impact

No impact to the product's functionality anticipated

### Data sheet revision

No impact to existing datasheet

### Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 07 Aug 2024. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## Additional information

[View Change Notification Online](#)

## Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: [pcn@nexperia.com](mailto:pcn@nexperia.com)

In case of distribution, please contact you distribution partner.

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